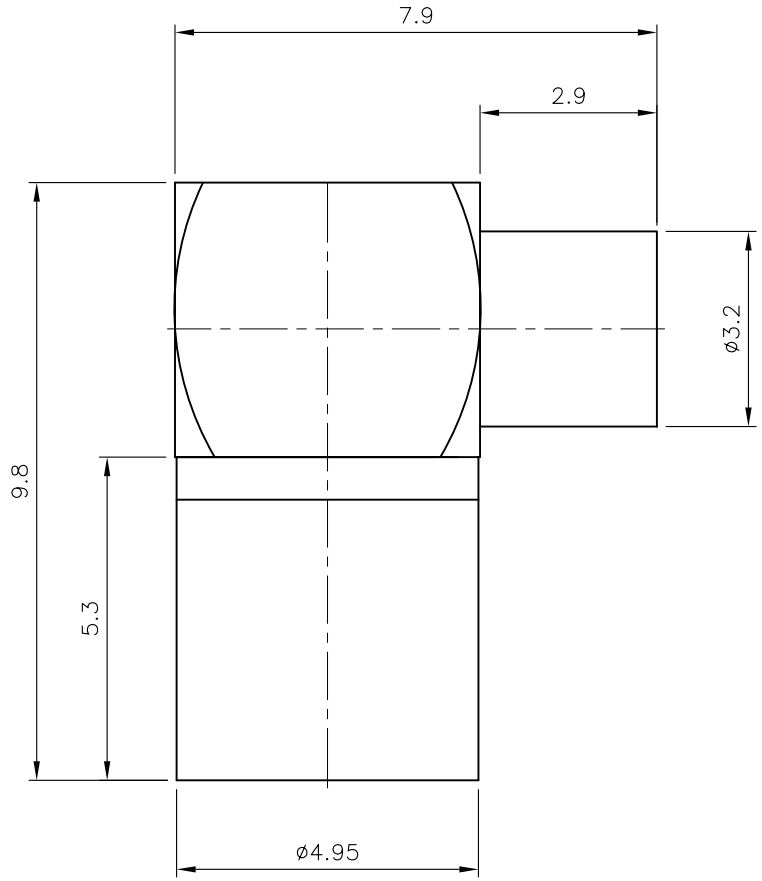
REVISION

REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration			2004.07.22.
1	[설변처리No.201308-0003] 조립성 개선 (TEFLON변경)	E.H.KIM	I.C.KIM	2013.08.08.



	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE	
	7	SPRING RING	1	BeCu	Gold Plate	DSR00037-5/1	
	6	COVER	1	MBsBD	Gold Plate	DCU00039-5/1	
	5	CAP	1	MBsBD	Gold Plate	DCO00011-5/1	
1	4	INSULATOR	~~2~~ 1	TEFLON		DIN00939-N/1 ~~DIN00927-N/1~~	
	3	INSULATOR	1	TEFLON		DIN00365-N/1	
	2	CONTACT	1	BeCu	Gold Plate	DCT00425-5/1	
	1-2	BODY	1	MBsBD	Gold Plate	DBB00086-5/1	DBD00530-3/1
	1-1	BODY	1	MBsBD	Gold Plate		DBD00526-1/1

TOLERANCE	Decimal ±0.2	DATE	2013. 08. 08.
	Angle ±1°	APPROVED BY	I.C.KIM
MATERIAL		CHECKED BY	
		DRAWN BY	E.H.KIM
FINISH		SCALE 8/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
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TITLE
SMF50 CABLE JL 85TP(50Ω)

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